

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>David Wei WANG</td> <td>12/09/2010</td> </tr> <tr> <td>An-Hong LIU</td> <td>12/08/2010</td> </tr> <tr> <td>Hsiang-Ming HUANG</td> <td>12/08/2010</td> </tr> <tr> <td>Jar-Dar YANG</td> <td>12/08/2010</td> </tr> <tr> <td>Yi-Chang LEE</td> <td>12/08/2010</td> </tr> </tbody> </table>		Name	Execution Date	David Wei WANG	12/09/2010	An-Hong LIU	12/08/2010	Hsiang-Ming HUANG	12/08/2010	Jar-Dar YANG	12/08/2010	Yi-Chang LEE	12/08/2010
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<b>RECEIVING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;">Name:</td> <td>CHIPMOS TECHNOLOGIES INC.</td> </tr> <tr> <td>Street Address:</td> <td>No.1, R&amp;D Rd.1, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu city</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	CHIPMOS TECHNOLOGIES INC.	Street Address:	No.1, R&D Rd.1, Science-Based Industrial Park	City:	Hsinchu city	State/Country:	TAIWAN				
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<b>PROPERTY NUMBERS Total: 1</b>													
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<b>CORRESPONDENCE DATA</b>													
<p>Fax Number: (206)203-2603</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 301-840-3885</p> <p>Email: MCHOW@SINORICA.COM</p> <p>Correspondent Name: SINORICA, LLC</p> <p>Address Line 1: 2275 Research Blvd.</p> <p>Address Line 2: Suite 500</p> <p>Address Line 4: ROCKVILLE, MARYLAND 20850</p>													
ATTORNEY DOCKET NUMBER:	TW-GNA-0906												
NAME OF SUBMITTER:	Ming Chow												
Total Attachments: 2													

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**PATENT**  
**REEL: 025623 FRAME: 0623**

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**PATENT**

**REEL: 025623 FRAME: 0624**

## ASSIGNMENT DEED

This assignment agreement is applicable to an invention entitled (invention title) \_\_\_\_\_

Multi-chip stack package structure

This PATENT RIGHT referred to in this agreement is (check one):

☒ a Patent Application for this invention, executed by the ASSIGNOR(S) concurrently with this Agreement.

☐ U.S. Patent Application Serial No. \_\_\_\_\_, filed on \_\_\_\_\_

☐ U.S. patent No. \_\_\_\_\_, issued on \_\_\_\_\_

The PATENT RIGHT assigned under this agreement is:

☒ U.S. Patent rights only

☐ worldwide Patent rights (the assignee shall have the right to claim the benefit for the filing date of any U.S. Patent Application identified above).

The ASSIGNOR(S) referred to in this agreement is (or are):

David Wei Wang (full name of first assignor)

No.1. R&D Rd.1, Science-Based Industrial Park, Hsinchu city, Taiwan(R.O.C.) (address)

The ASSIGNOR(S) referred to in this agreement is (or are):

An-Hong Liu (full name of second assignor)

No.1. R&D Rd.1, Science-Based Industrial Park, Hsinchu city, Taiwan (R.O.C.) (address)

The ASSIGNOR(S) referred to in this agreement is (or are):

Hsiang-Ming Huang (full name of third assignor)

No.1. R&D Rd.1, Science-Based Industrial Park, Hsinchu city, Taiwan (R.O.C.) (address)

The ASSIGNOR(S) referred to in this agreement is (or are):

Jar-Dar Yang (full name of fourth assignor)

No.1. R&D Rd.1, Science-Based Industrial Park, Hsinchu city, Taiwan (R.O.C.) (address)

The ASSIGNOR(S) referred to in this agreement is (or are):

Yi-Chang Lee (full name of fifth assignor)

No.1. R&D Rd.1, Science-Based Industrial Park, Hsinchu city, Taiwan (R.O.C.) (address)

The First ASSIGNEE referred to in this agreement is:

CHIPMOS TECHNOLOGIES INC. (full name of first assignee)

No.1. R&D Rd.1, Science-Based Industrial Park, Hsinchu city, Taiwan (R.O.C.) (address)

Is (check one): ☐ an individual ☐ a partnership ☒ a Corporation of Taiwan (R.O.C.)  
(State or Country)

The second ASSIGNEE referred to in this agreement is:

\_\_\_\_\_ (full name of first assignee)

\_\_\_\_\_ (address)

Is (check one): ☐ an individual ☐ a partnership ☐ a Corporation of \_\_\_\_\_  
(State or Country)

## ASSIGNMENT DEED

The ASSIGNOR(S), in consideration of \$1.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, have and do hereby assign the following to each ASSIGNEE, their successors and assigns:

the full and exclusive right to the invention;

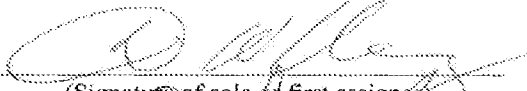
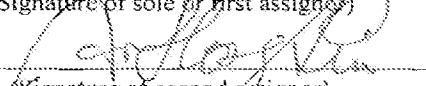
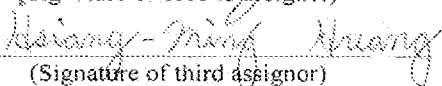
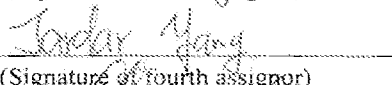
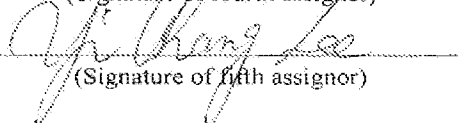
an equal interest in and to the entire right, title and interest in and to the PATENT RIGHTS in the invention;

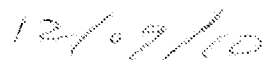
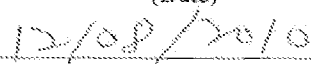
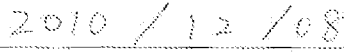
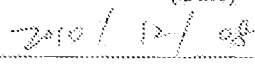
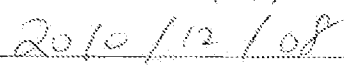
all continuations, continuations-in-part, divisionals, re-issues, and re-examination patents and patent applications; and

the right to claim priority under 35 U.S.C. 119, based on any earlier foreign applications for this invention.

As to all U.S. Patent Applications assigned under this Agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Director of Patents and Trademarks to issue all Letters Patent to the ASSIGNEE(S) as the ASSIGNEE(S) of an equal interest in the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE(S), their successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE(S), or their representatives, and facts known to the ASSIGNOR(S) respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause any and all Letters Patent to be issued to said ASSIGNEE(S), make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE(S), their successors and assigns, to obtain an enforced proper protection for said invention.

  
(Signature of sole or first assignor)  
  
(Signature of second assignor)  
  
(Signature of third assignor)  
  
(Signature of fourth assignor)  
  
(Signature of fifth assignor)

  
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